INTEGRATED CIRCUITS

DATA SHEET

74LVC109

Dual JK flip-flop with set and reset; positive-edge trigger

Product specification Supersedes data of 1997 Mar 18 IC24 Data Handbook







Philips Semiconductors Product specification

Dual JK flip-flop with set and reset; positive-edge trigger

74LVC109

FEATURES

- Wide supply voltage range of 1.2 to 3.6 V
- In accordance with JEDEC standard no. 8-1A.
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output capability: standard
- I_{CC} category: flip-flops

DESCRIPTION

The 74LVC109 is a low-voltage Si-gate CMOS device that is pin and function compatible with 74HC/HCT109.

The 74LVC109 is a dual positive-edge triggered JK-type flip-flop featuring individual J, \overline{K} inputs, clock (CP) inputs, set (\overline{S}_D) and reset (\overline{R}_D) inputs; also complementary Q and \overline{Q} outputs.

The set and reset are asynchronous active LOW inputs and operate independently of the clock input.

The J and \overline{K} inputs control the state changes of the flip-flops as described in the mode select function table. The J and \overline{K} inputs must be stable one set-up time prior to the LOW-to-HIGH clock transition for predictable operation. The $J\overline{K}$ design allows operation as a D-type flip-flop by tying the J and \overline{K} inputs together.

Schmitt-trigger action in the clock input makes the circuit highly tolerant to slower clock rise and fall times.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay nCP to nQ, n \overline{Q} n \overline{S}_D to nQ, n \overline{Q} n \overline{R}_D to nQ, n \overline{Q} n \overline{R}_D to nQ, n \overline{Q}	C _L = 50 pF; V _{CC} = 3.3 V	4.0 4.5 4.5	ns
f _{max}	Maximum clock frequency		250	MHz
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per flip-flop	$V_I = GND \text{ to } V_{CC}^1$	27	pF

NOTE:

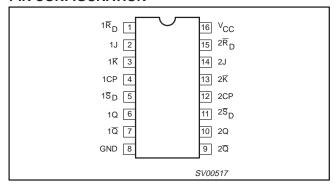
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: $f_i = \text{input frequency in MHz; } C_L = \text{output load capacity in pF; } f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V;}$

 $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
16-Pin Plastic SO	-40°C to +85°C	74LVC109 D	74LVC109 D	SOT109-1
16-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC109 DB	74LVC109 DB	SOT338-1
16-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC109 PW	74LVC109PW DH	SOT403-1

PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 15	1R _D , 2R _D	Asynchronous reset input (active LOW)
2, 14, 3, 13	1J, 2J, 1K, 2K	Synchronous inputs; flip-flops 1 and 2
4, 12	1CP, 2CP	Clock input (LOW-to-HIGH, edge-triggered)
5, 11	1\$\overline{S}_D, 2\$\overline{S}_D	Asynchronous set inputs (active LOW)
6, 10	1Q, 2Q	True flip-flop outputs
7, 9	1Q, 2Q	Complement flip-flop outputs
8	GND	Ground (O V)
16	V _{CC}	Positive supply voltage

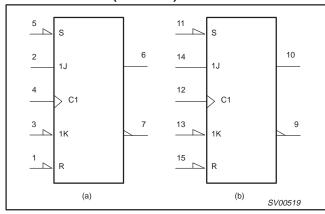
^{1.} C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

Philips Semiconductors Product specification

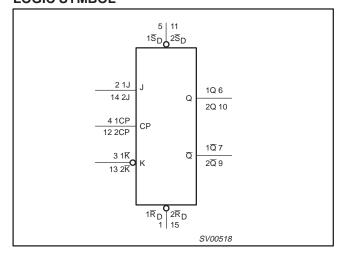
Dual JK flip-flop with set and reset; positive-edge trigger

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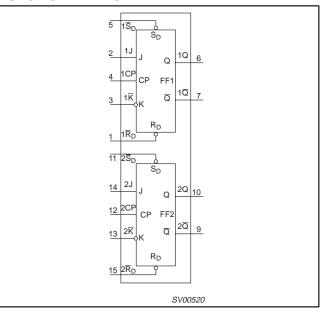
LOGIC SYMBOL (IEEE/IEC)



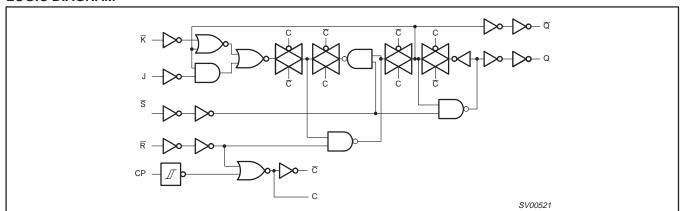
LOGIC SYMBOL



FUNCTIONAL DIAGRAM



LOGIC DIAGRAM



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FUNCTION TABLE

OPERATING MODES			INPUTS			OUTPUTS		
OPERATING MODES	nS _D	nR _D	nCP	nJ	nK	nQ	nQ	
Asynchronous set	L	Н	Х	Х	Х	Н	L	
Asynchronous reset	Н	L	X	X	X	L	Н	
Undetermined	L	L	X	Х	Х	Н	Н	
Toggle	Н	Н	↑	h	I	q	q	
Load "0" (reset)	Н	Н	\uparrow	ı	I	L	Н	
Load "1" (set)	Н	Н	\uparrow	h	h	Н	L	
Hold "no change"	Н	Н	↑	I	h	q	q	

NOTES:

H = HIGH voltage level

- h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition
- L = LOW voltage level
- I = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition
- q = lower case letters indicate the state of the referenced output one set-up time prior to the LOW-to-HIGH CP transition.
- X = don't care
- ↑ = LOW-to-HIGH CP transition

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STWIBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage (for max. speed performance)		2.7	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC input voltage range		0	5.5	V
V _O	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	$V_I < 0$	-50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
I _{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
Vo	DC output voltage	Note 2	-0.5 to V _{CC} +0.5	V
Io	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
 device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
 absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

			L	IMITS				
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	Temp = -40°C to +85°C				
			MIN	TYP ¹	MAX]		
V	HICH level Input voltage	V _{CC} = 1.2V	V _{CC}			V		
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0]		
V	LOW lovel land voltage	V _{CC} = 1.2V			GND	V		
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V			0.8	1 ^v		
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12mA$	V _{CC} -0.5					
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	LUCI Lloyal autout valtage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -100\mu A$	V _{CC} -0.2	V _{CC}				
V _{OH}	HIGH level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = -12\text{mA}$	V _{CC} -0.6]		
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -24$ mA	V _{CC} - 1.0]		
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12mA$			0.40			
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		GND	0.20	V		
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 24$ mA			0.55			
I _I	Input leakage current	V _{CC} = 3.6V; V _I = 5.5V or GND		±0.1	±5	μΑ		
I _{CC}	Quiescent supply current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}; I_O = 0$		0.1	10	μΑ		
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V; I_O = 0$		5	500	μА		

NOTE:

AC CHARACTERISTICS

GND = 0 V; t_r = $t_f \leq$ 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C

					LIM	ITS			
SYMBOL	PARAMETER	WAVEFORM	Vcc	= 3.3V ±0).3V	,	/ _{CC} = 2.7\	/	UNIT
			MIN	TYP ¹	MAX	MIN	TYP NO TAG	MAX	
t _{PHL} /t _{PLH}	Propagation delay nCP to nQ, nQ	Figures 1, 3		4.3	7.5			8.5	ns
t _{PLH}	Propagation delay nS _D to nQ nR _D to nQ	Figures 2, 3		4.5	8.0			9.0	ns
t _{PHL}	Propagation delay nSD to nQ nRD to nQ	Figures 2, 3		5.2	9.0			10	ns
t _W	Clock pulse width HIGH or LOW	Figure 1	3.3	2.0					ns
t _W	Set or reset pulse width HIGH or LOW	Figure 2	3.0						ns
t _{rem}	Removal time $n\overline{S}_{D_i}$ $n\overline{R}_{D}$ to nCP	Figure 2	3.0						ns
t _{su}	Set-up time nJ, nK to CP	Figure 1	2.5						ns
t _h	Hold time nJ, nK to nCP	Figure 1	2.0						ns
f _{max}	Maximum clock pulse frequency	Figure 1	150	225					MHz

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NOTE:

^{1.} All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

^{1.} These typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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AC WAVEFORMS

 V_M = 1.5 V at $V_{CC} \geq$ 2.7 V; V_M = 0.5 \times V_{CC} at V_{CC} < 2.7 V.

 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

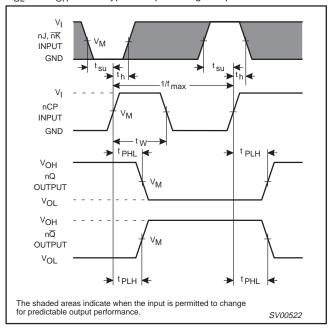


Figure 1. Clock (nCP) to output (nQ, nQ) propagation delays, the clock pulse width, the nJ and nK to nCP set-up, the nCP to nJ, nK hold times and the maximum clock pulse frequency.

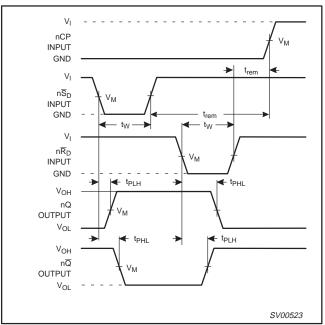


Figure 2. Set $(n\overline{S}_D)$ and reset $(n\overline{R}_D)$ input to output $(nQ, n\overline{Q})$ propagation delays, the set and reset pulse widths and the $n\overline{R}_D$, $n\overline{S}_D$ to nCP removal time.

TEST CIRCUIT

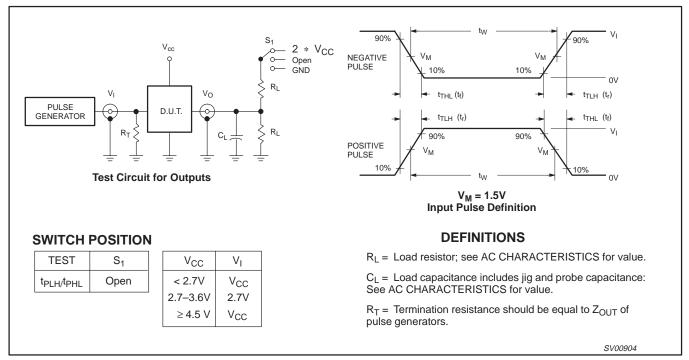


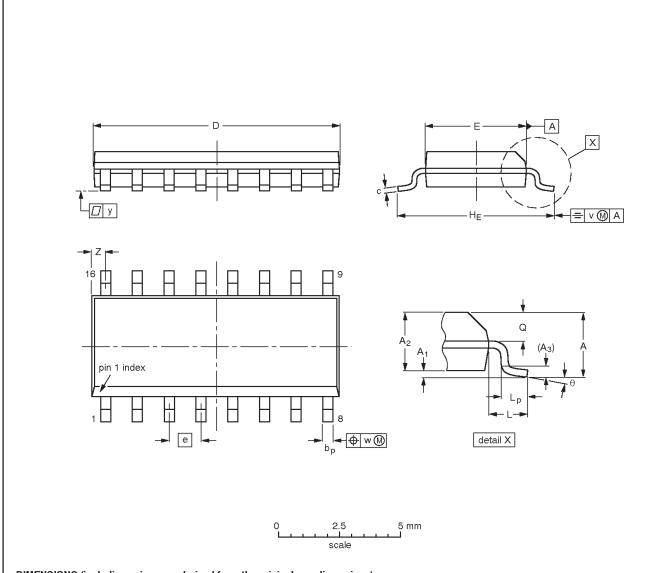
Figure 3. Load circuitry for switching times.

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

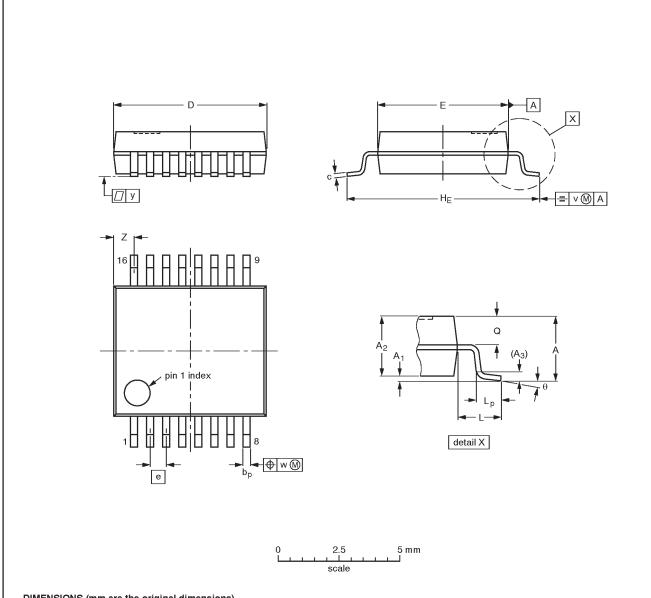
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1330E DATE
SOT109-1	076E07S	MS-012AC			95-01-23 97-05-22

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SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	рb	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8° 0°

Note

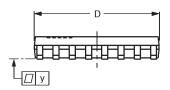
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

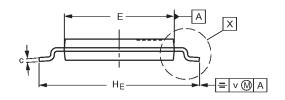
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC JEDEC EIAJ				PROJECTION	ISSUE DATE	
SOT338-1		MO-150AC				94-01-14 95-02-04	

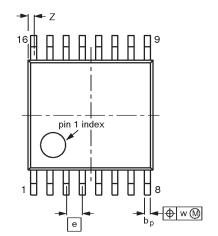
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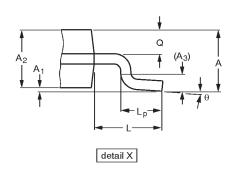
TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1











DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	c	D ⁽¹⁾	E ⁽²⁾	Φ	HE	٦	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1990E DATE	
SOT403-1		MO-153				-94-07-12 95-04-04	

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DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philip Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.				

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